

ABSTRACT OF THE DISCLOSURE

METHOD OF REGULATING A SURFACE TEMPERATURE OF POLISHING PAD, AND POLISHING APPARATUS

A method capable of precisely regulating a surface temperature of a polishing pad is disclosed. The method includes: determining a heating-side manipulation range by removing a dead band of a first flow-rate control valve from a range of manipulated variable for the first flow-rate control valve; setting a first manipulated variable, selected from the heating-side manipulation range, to the first flow-rate control valve; determines a cooling-side manipulation range by removing a dead band of a second flow-rate control valve from a range of manipulated variable for the second flow-rate control valve; setting a second manipulated variable, selected from the cooling-side manipulation range, to the second flow-rate control valve; and supplying a heating fluid and a cooling fluid that have passed through the flow-rate control valves to a heat exchanger to regulate a surface temperature of a polishing pad.

FIG. 2